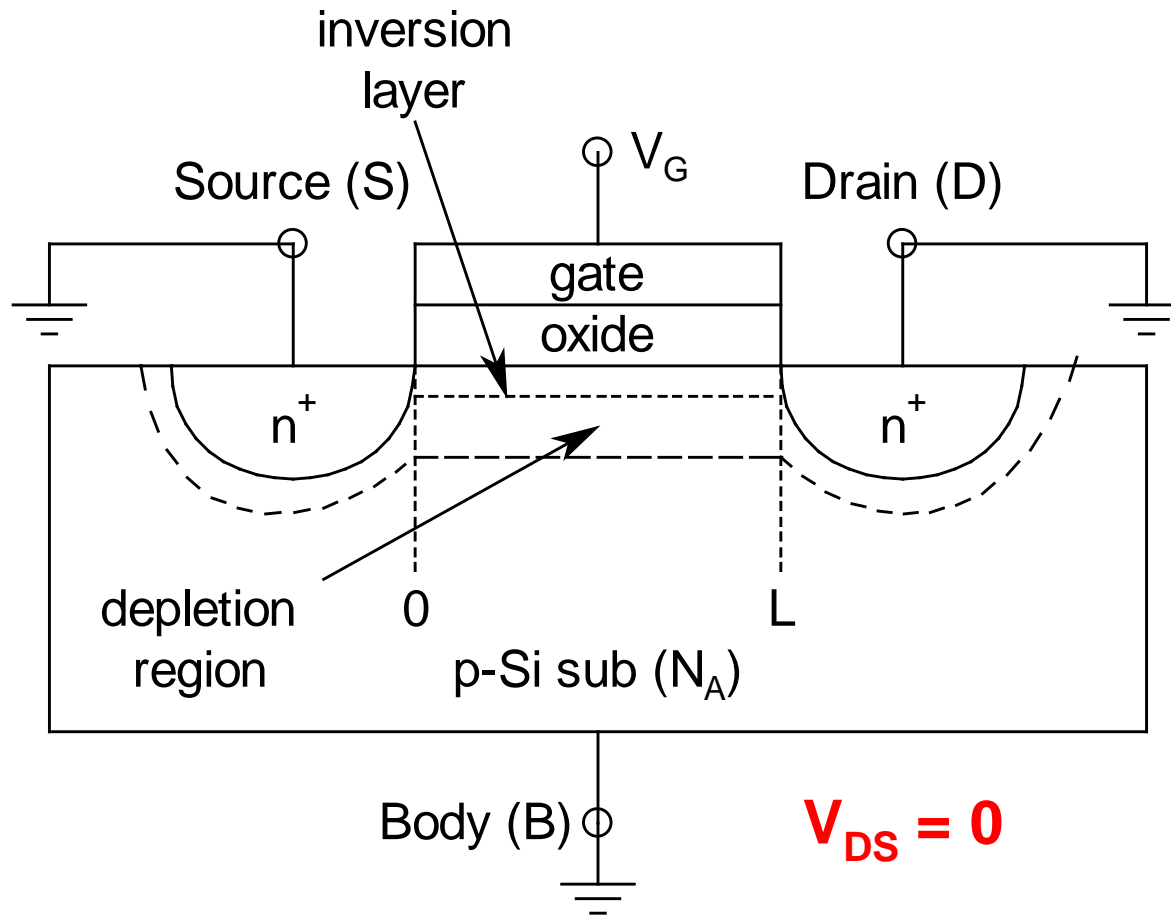


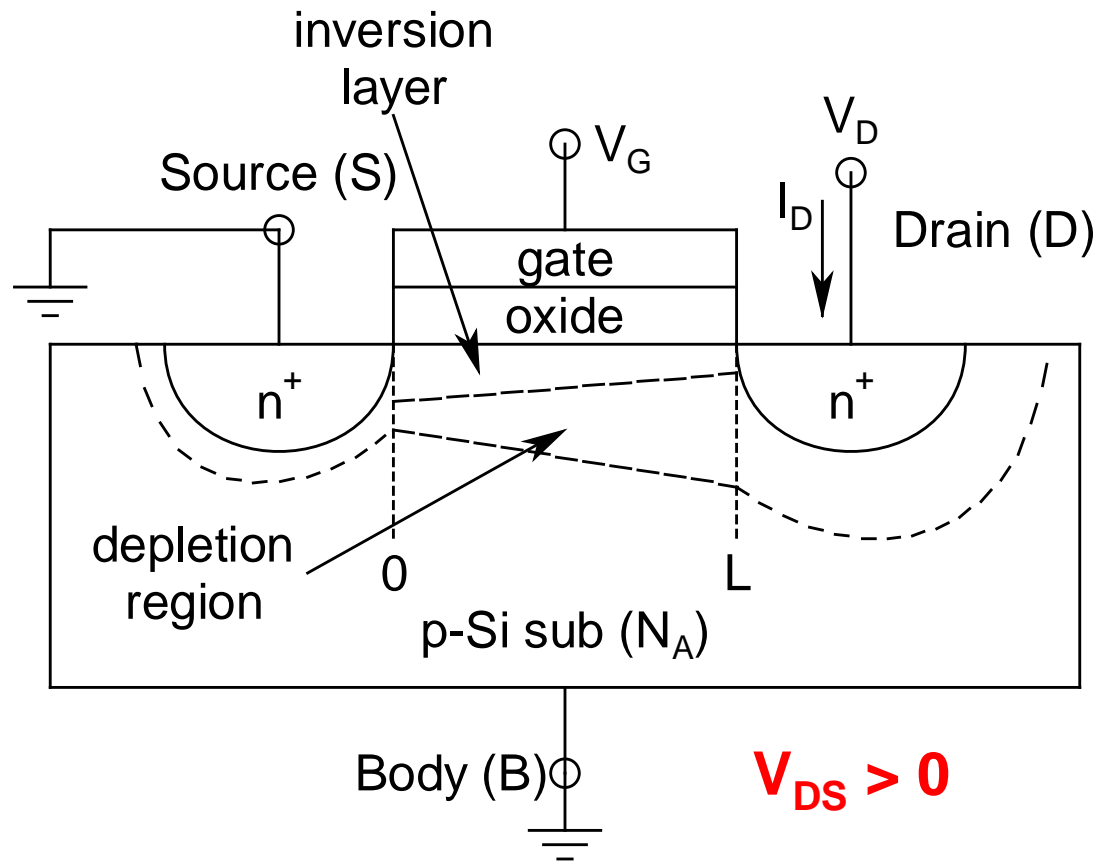
Operation



- The structure is *similar* to an n^+pn^+ *BJT*
- However, *BJT action* is *not possible* due to *large channel length* (L)
- The way to make the device *conduct* is to form a *layer of electrons* between S and D
 - Known as *Inversion Layer*
- Then, if a *bias* is applied *between S and D*, then *inversion layer electrons* will move *towards the higher potential* due to *drift*
 - A *current* would result

- Consider $V_S = V_D = V_B = V_G = 0$
 - Device is *off* and *no current flows*
- Note that the *structure* is similar to a *capacitor*
- Now, as V_G is made *positive*, initially it will *repel holes from surface towards bulk*, *uncovering ionized acceptor atoms there*
 - *Formation of a depletion layer*
- There will be *depletion layers* around *SB and DB junctions* as well

- As V_G is kept on *increasing*, the *depletion charge* will keep on *increasing*
- At a *certain value* of V_G ($= V_{GS}$), a *layer of electrons* will *appear at the surface*
- This *particular value* of V_{GS} is known as the *threshold voltage* V_{TN}
- Still *no current* would flow, since $V_{DS} = 0$
- *SB and DB junctions* must remain *either at zero bias or reverse bias* all the time
 - V_{SB} and $V_{DB} \geq 0$



- With $V_{DS} > 0$, *inversion layer electrons* will *move* towards the *higher potential*, i.e., D
 - The *drain current* I_D would *flow from D to S*
- *Note:*
 - The *depletion charge* would *increase* as we move *towards the D* (since the *DB junction* is *more reverse biased*)
 - The *inversion charge* would *decrease* as we move *towards the D* (to balance the gate charge)
 - For *sufficiently high* V_{DS} , it may *disappear altogether at the drain end*

Body Effect

- The *threshold voltage* V_{TN} is a *function* of the *SB voltage* V_{SB}
- As $V_{SB} \uparrow$, the *SB junction depletion charge* would *increase*
 - For the *same* V_{GS} , *inversion charge* would *decrease* (to maintain *charge balance*)
 - Thus, to *restore* the *original level* of *inversion*, V_{GS} has to be *increased*
 - Implies that V_{TN} has *increased*

- Expressed as:

$$V_{\text{TN}} = V_{\text{TN0}} + \gamma \left(\sqrt{2\phi_{\text{F}} + V_{\text{SB}}} - \sqrt{2\phi_{\text{F}}} \right)$$

$$V_{\text{TN0}} = V_{\text{TN}} \big|_{V_{\text{SB}}=0} = \textit{Zero back-bias threshold voltage}$$

$$\gamma = \frac{\sqrt{2q\epsilon_s N_{\text{A}}}}{C'_{\text{ox}}} = \textit{Body-effect coefficient}$$

$$C'_{\text{ox}} = \frac{\epsilon_{\text{ox}}}{t_{\text{ox}}} = \textit{Oxide capacitance per unit area}$$

$$\phi_{\text{F}} = V_{\text{T}} \ln \left(\frac{N_{\text{A}}}{n_{\text{i}}} \right) = \textit{Bulk potential} \ (\sim 0.3 - 0.45 \text{ V})$$

Current-Voltage Relation

- For $V_{GS} > V_{TN}$ and *small* V_{DS} :

$$I_D = k_N \left(V_{GT} V_{DS} - V_{DS}^2 / 2 \right)$$

$$V_{GT} = V_{GS} - V_{TN} = \textit{Gate overdrive}$$

$$k_N = (W/L) k'_N$$

$= \textit{Device transconductance parameter}$

$$W/L = \textit{Aspect ratio}$$

$$k'_N = \mu_n C'_{ox}$$

= *Process transconductance parameter*

μ_n = *Channel electron mobility*

- For *small* V_{DS} , the V_{DS}^2 term can be *neglected*
 - I_D changes *linearly* with V_{DS}
 - *Linear* (or *Non-Saturation*) Region
- As $V_{DS} \uparrow$, the *restraining* effect of V_{DS}^2 term \uparrow
 - *Rate of increase* of I_D with V_{DS} *slows down*

- For *inversion channel* to exist at the *D end*,
 V_{GD} must be $> V_{TN}$
 - V_{DS} must be $< V_{GT}$
- When $V_{DS} = V_{GT}$, the *channel* is said to be *pinched-off* at the *D end*, and I_D does not increase any more
- This value of V_{DS} is known as the *drain-to-source saturation voltage* $V_{DS,sat}$
 - $V_{DS,sat} = V_{GT}$